

# RELEASE FILM ECO 25

ECO25 – Release Film is a very economical solution to be used in all different types of lamination processes. The maximum laminating temperature is 200°C.

ECO25– Release Film is an inert or non reactive material and leaves no residues on the PCB –surfaces. Excellent functional and

dimensional properties under common thermal conditions and high pressure guarantees a very easy release.

Typical usage: FPC, Rigid-Flex PCB, HDI and CCL lamination

## PROPERTIES

Thermal usage in the hot press	max. 200 °C (392 °F) for 90min.	
Melting point	250 °C ± 10 °C	
Density	1.400 gcm <sup>-3</sup>	ASTM-D1505
Tensile strength	MD ≥ 210 Nmm <sup>-2</sup> TD ≥ 210 Nmm <sup>-2</sup>	ASTM D882A ASTM D882A
Elongation at break (v= 50mm/min <sup>-1</sup> )	MD ≥ 110 % TD ≥ 110 %	ASTM D882A ASTM D882A
Heat shrinkage (150°C / 30min.)	MD ≤ 1.5 % TD ≤ 0 %	ASTM D1204 ASTM D1204
Coefficient of friction (static) Coefficient of friction (dynamic)	0.26 0.13	ASTM D1894 ASTM D1894
Decomposition temperature	> 270 °C	
Moisture absorption	< 0.9 % at common room conditions	
Appearance	white	
Haze	75%	ASTM-D1003
Surface	Matt - both sides, Ra < 4.3 µm	
Storage Life	> 1 year at room temperature	
Thickness	25, 38, 50 µm – 1.0, 1.5, 2.0 mm	
Length of film	1067 / 1000 / 500 m	
Roll widths	660, 680, 991, 1295 mm	

Subject to changes due to technical improvements without prior notice.

Other dimensions on request.